

Figure 1a

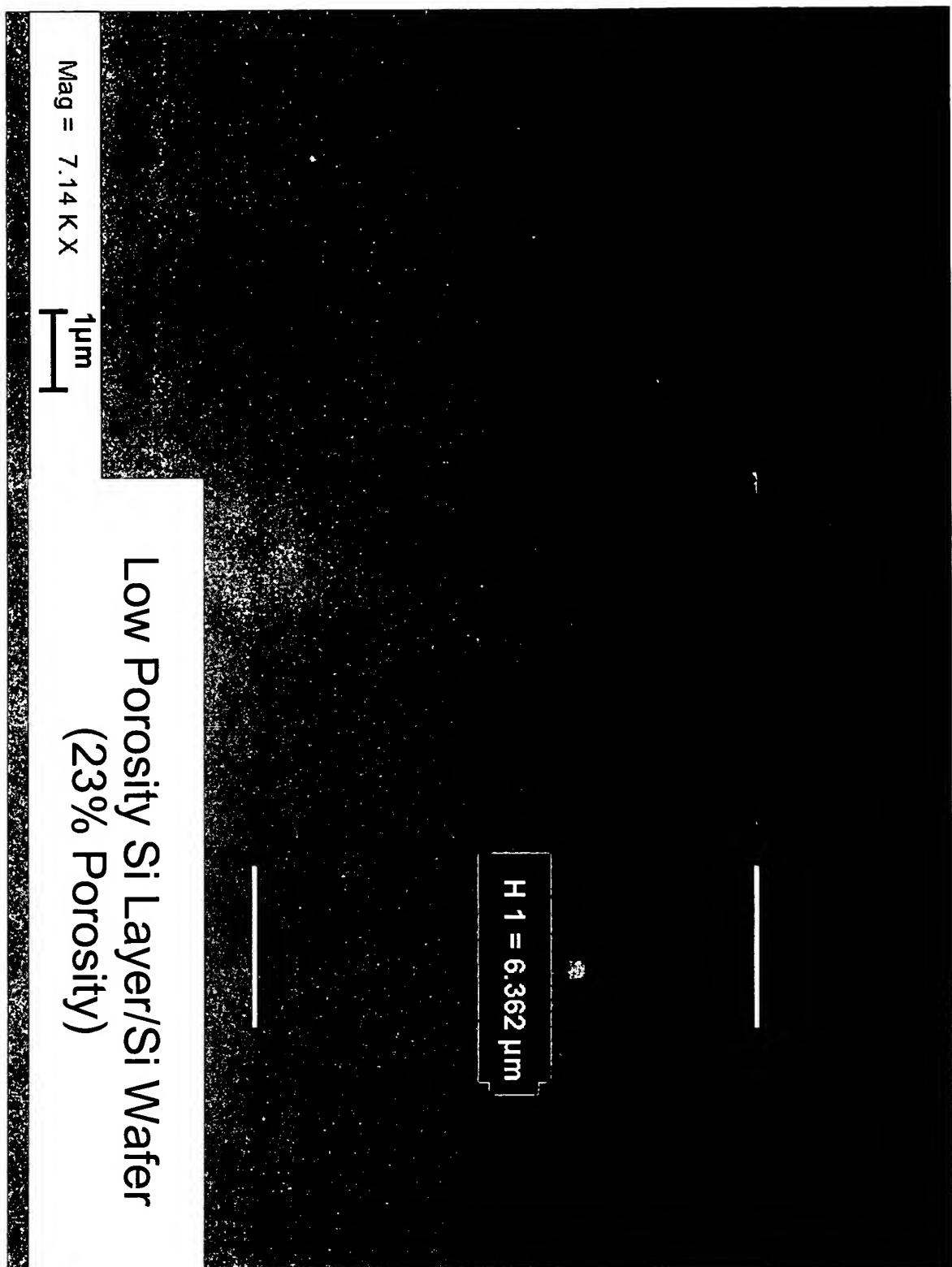


Figure 1b

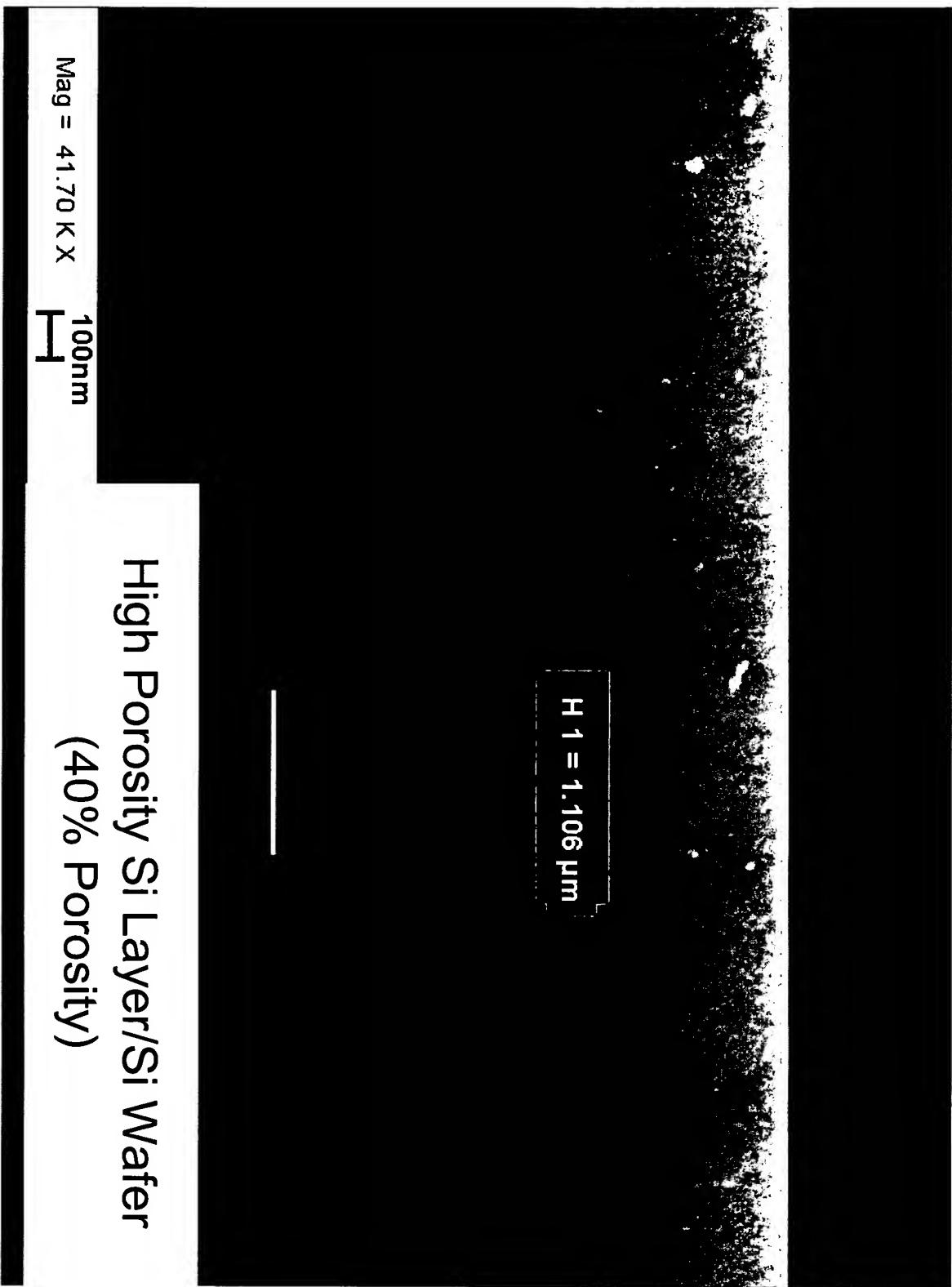


Figure 1c

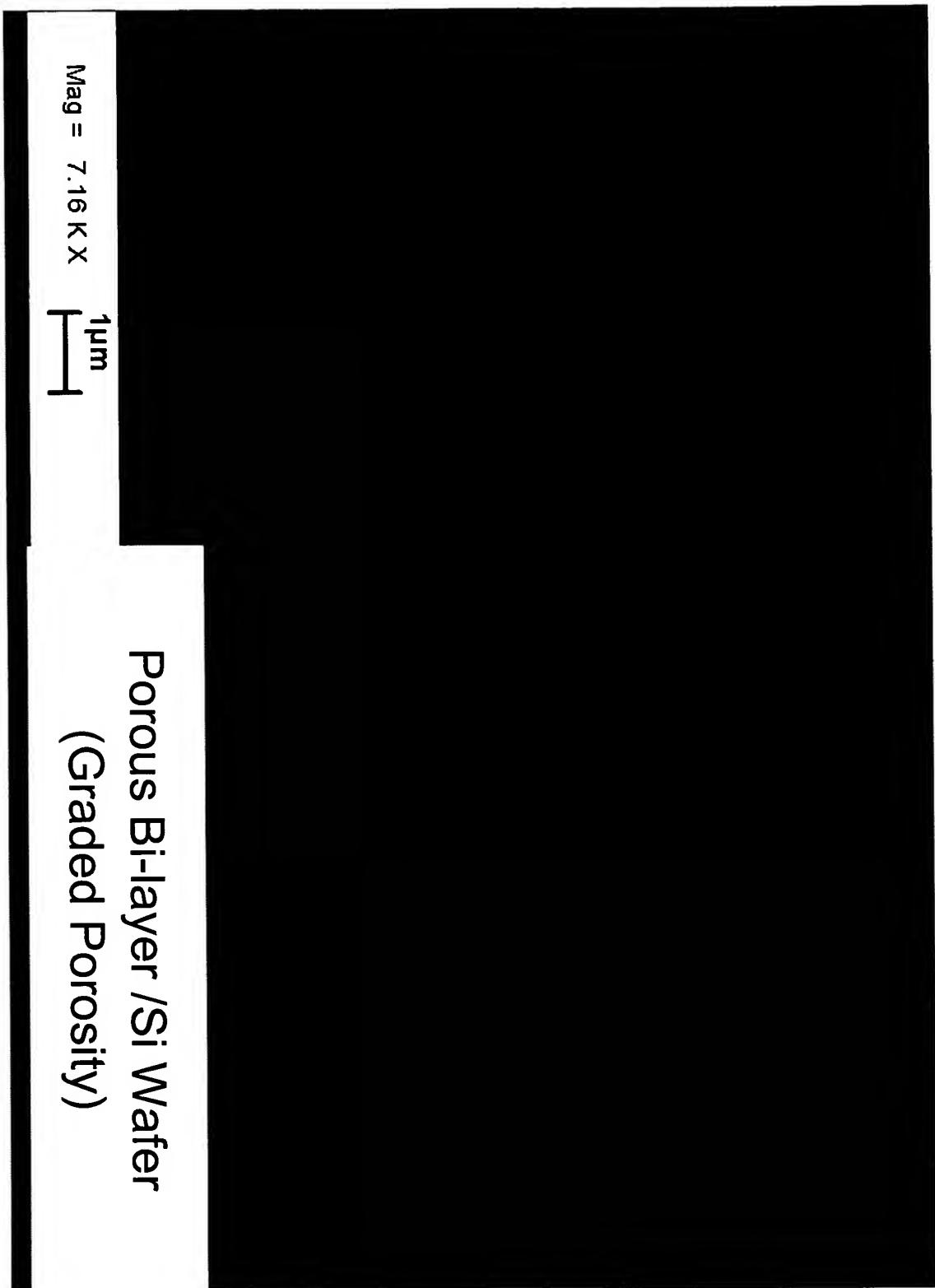
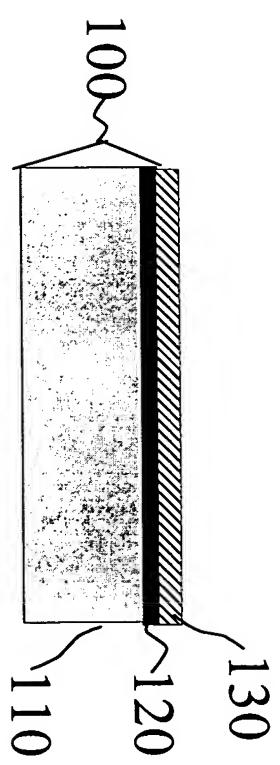


Figure 2



**substrate based on use of the porous-Si layer
and subsequent regrowth of epi-Si layer to create SOI wafers**

Figure 3

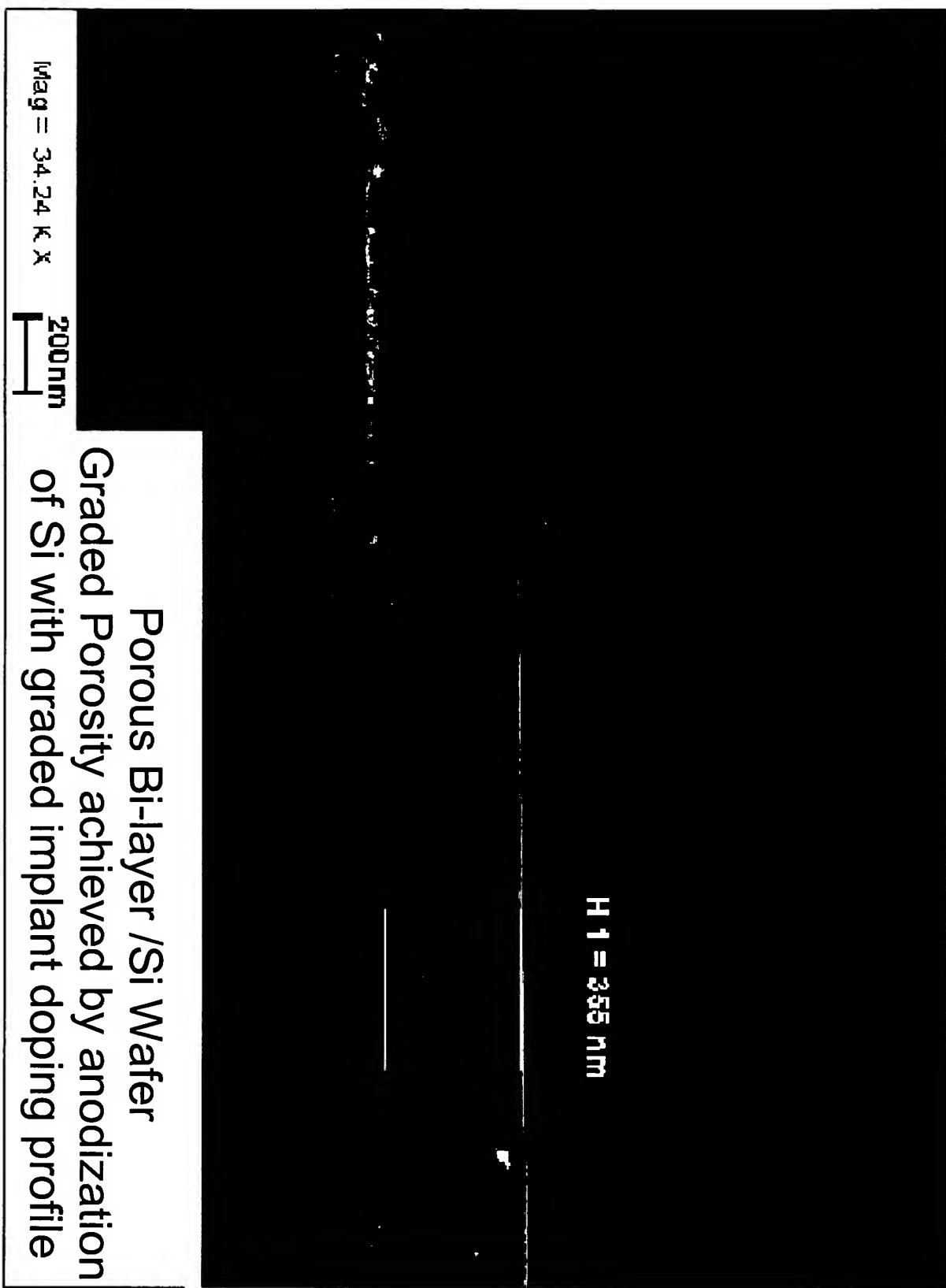
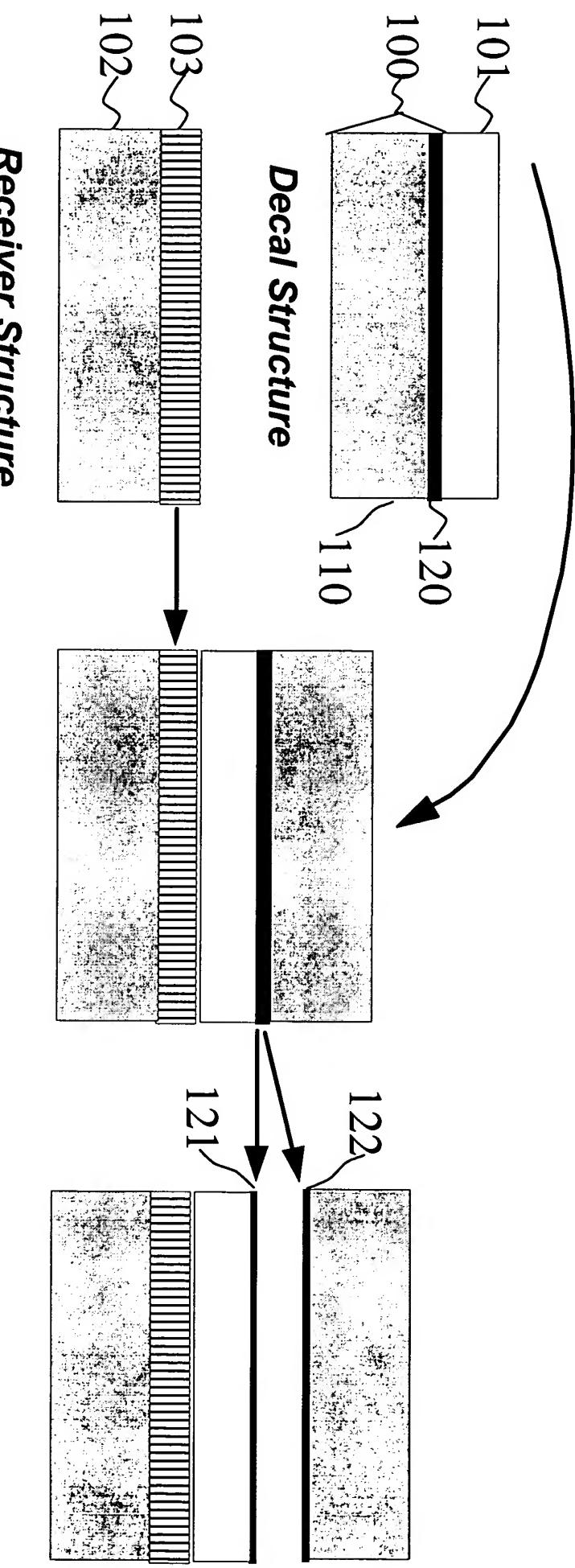


Figure 4



#1 Step: Build of Decal & Receiver Structures

#2 Step: Mating of Decal & Receiver Structures

#3 Step: Release of Carrier Substrate via Peeling

Figure 5

